MRD W. 23.98 Docket No. JCLA2434

DOCKC	11-04-19	98
Form 159 1-31-92		.S. Department of Commerce tatent and Trademark Office
	P ^A 10086792	20
To the Honorable Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.		
1. 1	Name of conveying party(ies):	2. Name/address of receiving Party(ies):
	Chi-Fa Lin	Winbond Electronics Corp.
	Nature of conveyance: ☒ Assignment ☐ Merger ☐ Security Agreement ☐ Other ☐ Change of Name ☐ Reassignment	No. 4, Creation Road. III, Science- Based Industrial Park, Hsinchu, Taiwan, R.O.C.
4. D	ate(s) of execution: September 1, 1998;	Add'I names of receiving parties Attached? Yes No
5. A	Application number(s) or patent number(s):	
	this documents is being filed tog execution date of the application is S . Patent Application No. (s)	
	09/178464 Additional numbers attached	? □ Yes ☒ No
C	Name and address of party to whom orrespondence concerning document hould be mailed:	Total No. of applications and patents involved: ONE(1)
	C.C. Patents, Inc.	8. Total fee (37 CFR §3.41): \$40.00
1	340 Reynolds Ave., Suite 114 rvine, CA 92614	⊠ Enclosed
	949) 660-0761	9. Total number of pages, including cover sheet, attachments and document 3.
DO NOT USE THIS SPACE		
10. St	atement and Signature:	
	To the best of my knowledge and belie and correct and any attached copy is a tru	
	ne of Person Signing Signatur	$\frac{100/23/99}{\text{Date}}$

Provisional Registration No. P-43, 330

PATENT REEL: 9548 FRAME: 0028 **ASSIGNMENT**

WHEREAS. Chi-Fa Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as

described and set forth in the below identified application for United States Letters Patent:

Title: STRUCTURE FOR A MULTI-LAYERED DIELECTRIC LAYER AND

MANUFACTURING METHOD THEREOF

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Winbond Electronics Corp., of No. 4, Creation Road III, Science-Based Industrial Park,

Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said

invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and

valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have

sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the

said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in

and to the said invention and application and all future improvements thereon, and in and to any

Letters Patent which may hereafter be granted on the same in the United States, the said interest to

be held and enjoyed by said Assignee as fully and exclusively as it would have been held and

enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term

of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in

whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but

at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or

applications, execute, verify, acknowledge and deliver all such further papers, including applications

for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof,

and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters

Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's

successors and assigns.

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PATENT

REEL: 9548 FRAME: 0029

ASSIGNMENT CONTINUED

IN TESTINONT WHENEOF, Assignor has/hav	e signed his/her/their hame(s) on the date(s)
indicated.	
Signature Chifu Lin	Sep. 1, 1998
	date
Signature	date
Signature	date
Signature	date

RECORDED: 10/23/1998